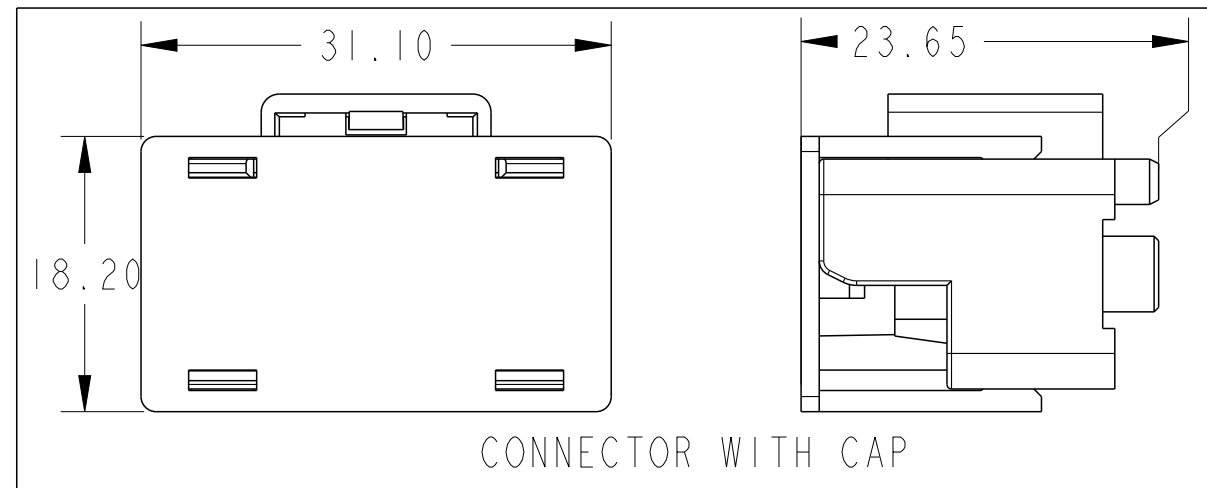
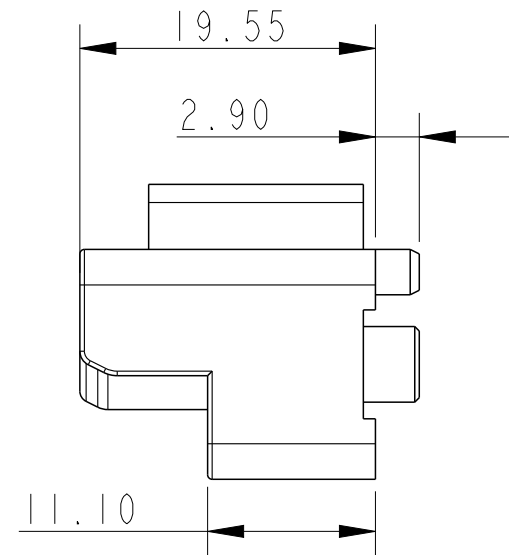
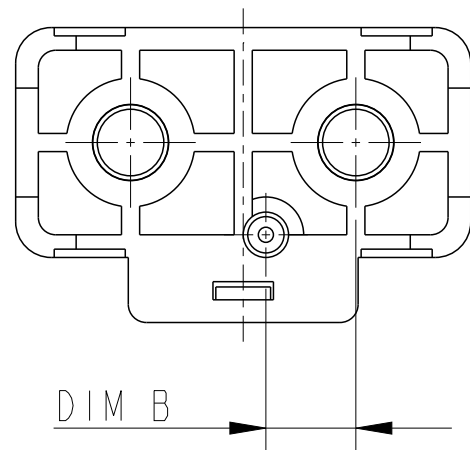
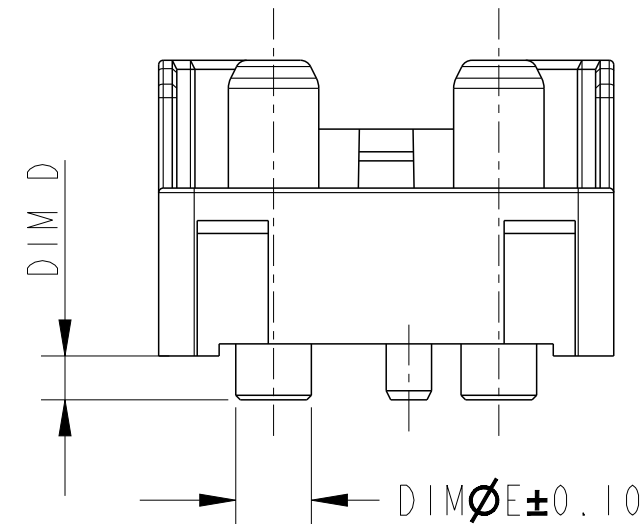
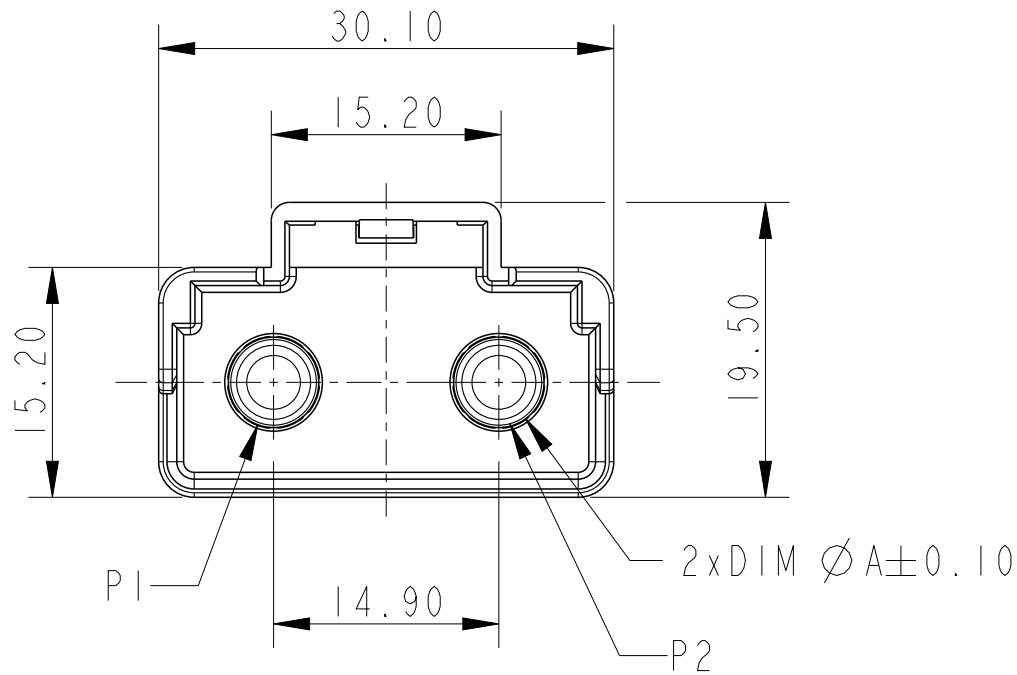
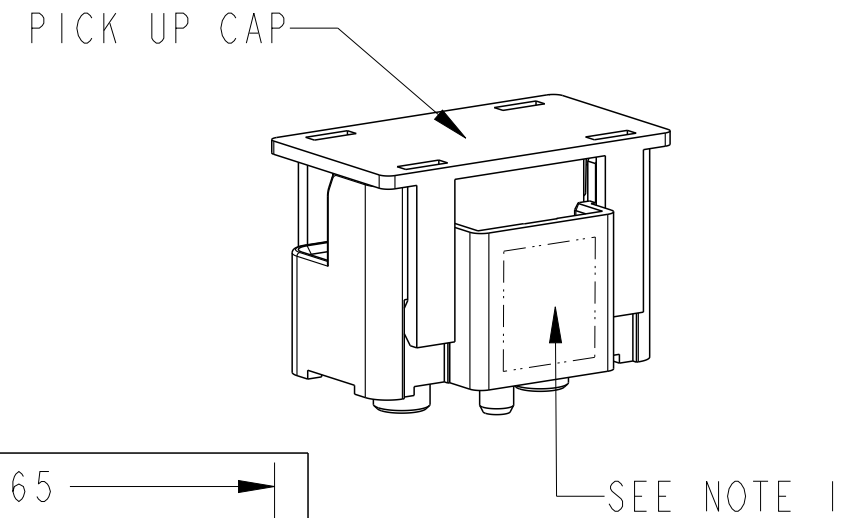




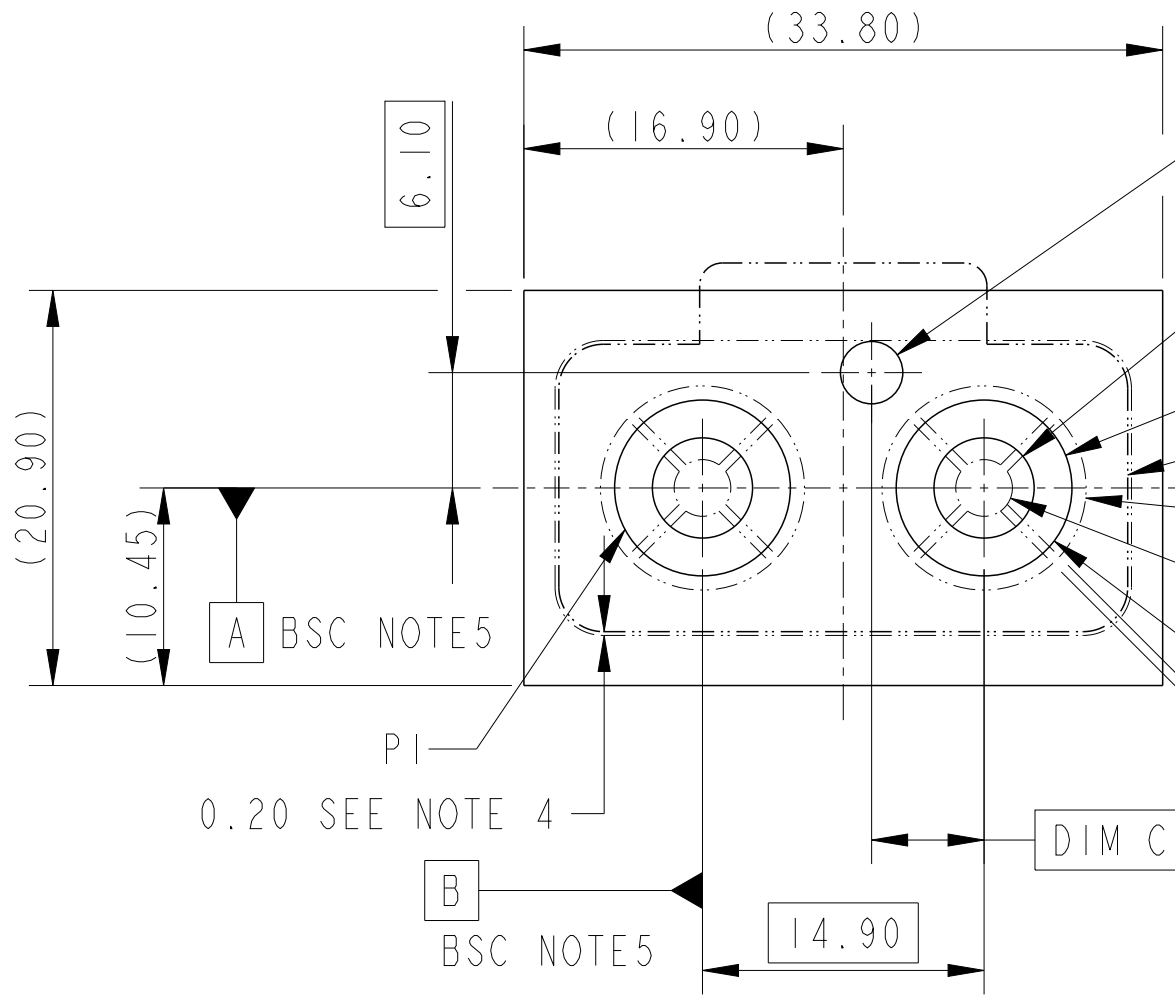
revision history				
rev	ecn no	description	dr	date
A	-	INITIAL RELEASE	Lu Chen	2026/03/05
-	-	-	-	YYYY/MM/DD
-	-	-	-	YYYY/MM/DD



SERIES	PART NUMBER	PACKAGING	SOLDERING	PICK UP CAP	DIM A	DIM B	DIM D	DIM E (Ø)
6.0MM 150A/PIN	*10174793-001LF	SOFT TRAY	DIP(WAVE SOLDERING)	NO	6.00	5.95	4.40	4.90
	*10174793-001CLF	JEDEC SOFT TRAY	PIP(REFLOW SOLDERING)	YES			2.90	5.00
	10174793-001PLF	HARD TRAY	PIP(REFLOW SOLDERING)	NO				
	10174793-001PCLF	HARD TRAY	PIP(REFLOW SOLDERING)	YES				
5.7MM 100A/PIN	*10174793-002LF	SOFT TRAY	DIP(WAVE SOLDERING)	NO	5.70	8.95	4.40	4.90
	*10174793-002CLF	JEDEC SOFT TRAY	PIP(REFLOW SOLDERING)	YES			2.90	5.00
	10174793-002PLF	HARD TRAY	PIP(REFLOW SOLDERING)	NO				
	10174793-002PCLF	HARD TRAY	PIP(REFLOW SOLDERING)	YES				

* = NOT TOOLED

spec ref				dr		Sunny Qin		2025/02/17		Amphenol Power Solutions				←MM→		scale		2.000		size		A3																	
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED				eng		Dong, Qing-Fen						2026/03/06		ecn no				ELX-DG-280526-1																			
ISO 406 ISO 1101						rvwr		-						-		rel level				Released																			
surface ISO 1302 ✓				linear		0.X		±0.5		projection				title		COOLPOWER HD 6.0MM & 5.7MM RA BOARD ASSEMBLY								dwg no		10174793						rev		A					
						0.XX		±0.25																cat. no.				-											
						0.XXX		±0.13																angular		0°		±°											
product family										-										Product - Customer Drw										sheet 1 of 2									



TOP VIEW
PCB LAYOUT
(RECOMMENDED STENCIL THICKNESS: 0.15MM)

$\varnothing 3.30 \pm 0.05$ NPTH
 $\varnothing 0.08$ A B
 $2 \times \varnothing 5.30 \pm 0.05$ PTH
 $\varnothing 0.08$ A B
 $(2 \times \varnothing 9.30)$ PAD

SEE NOTE 10
STENCIL OPENING, PIP ONLY
 $\varnothing 10.80$
STENCIL OPENING, PIP ONLY
 $\varnothing 3.00$
STENCIL OPENING, PIP ONLY
0.50 TYP.

2.40
RECOMMENDED PCB THICKNESS

- NOTE.
1. PRODUCT MARK PART NUMBER, MANUFACTURER'S NAME AND DATE CODE TO MARKED ON THIS SURFACE.
 2. MATERIALS:
 - HOUSING & PICK UP CAP: HIGH TEMP THERMOPLASTIC, UL94V-0, BLACK.
 - POWER CONTACT: HIGH CONDUCTIVITY COPPER ALLOY.
 3. PLATING SPECIFICATION:
TERMINALS: SILVER OVER NICKEL PLATING.
 4. DENOTES CONNECTOR KEEP OUT ZONE.
 5. DATUM AND BASIC DIMENIONS ARE ESTABLISHED BY CUSTOMER.
 6. ALL HOLE DIAMETERS ARE FINISHED HOLE SIZES.
 7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS FOR PIP(REFLOW SOLDERING)AND DIP(WAVE SOLDERING).
 8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.
 9. PRODUCT SPECIFICATION : GS-12-1941.
APPLICATION SPECIFICATION : GS-20-0908.
PRODUCT PACKAGE SPECIFICATION: GS-14-3141.
 10. THE MODULE LINE OF THE MOUL.

SERIES	PCB APPLICATION	DIM C
6.0MM 150A/PIN	10174793-001LF	5.95
	10174793-001CLF	
	10174793-001PLF	
	10174793-001PCLF	
5.7MM 100A/PIN	10174793-002LF	8.95
	10174793-002CLF	
	10174793-002PLF	
	10174793-002PCLF	

spec ref				dr		Sunny Qin	2025/02/17	Amphenol Power Solutions A Division of Amphenol Corporation amphenol-icc.com			MM		scale	2.500	size	A3
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng		Dong, Qing-Fen	2026/03/06				ec n no		ELX-DG-280526-1			
ISO 406 ISO 1101				r vwr		-	-				rel level		Released			
				appr		Andy Lu	2026/03/10									
surface ISO 1302		linear	0.X	±0.5	projection	title COOLPOWER HD 6.0MM & 5.7MM RA BOARD ASSEMBLY				dwg no	10174793				rev A	
			0.XX	±0.25												
			0.XXX	±0.13												
		angular	0°	±°												
product family						-		Product - Customer Drw				sheet 2 of 2				